PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data	
1.1 Company	STMicroelectronics International N.V
1.2 PCN No.	EMBEDDED PROCESSING/26/16402
1.3 Title of PCN	JCAP (China) additional source for STM32L476x, STM32L485x and STM32L486x listed products in WLCSP package
1.4 Product Category	STM32L476x, STM32L485x and STM32L486x in WLCSP package
1.5 Issue date	2026-10-28

2. PCN Team	
2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Patrick AIDOUNE
2.1.2 Marketing Manager	Marie TOURNUT
2.1.3 Quality Manager	Pascal NARCHE

3. Change		
3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	JCAP (China)

4. Description of change		
	Old	New
4.1 Description	Current assembly site : - ASE Kaohsiung (Taiwan) - Amkor ATT (Taiwan)	Assembly sites: - ASE Kaohsiung (Taiwan) - current Assembly sites - Amkor ATT (Taiwan) - current Assembly sites - JCAP (China) - new assembly site
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	- Form: Marking composition change. Slight RDL topology changes around some tiny location without impacting functionalities. - Fit: No impact: - No change on WLCSP dimensions - No change on ball characteristics - Function: No impact	

5. Reason / motivation for change	
5.1 Motivation	Second source introduction
5.2 Customer Benefit	CAPACITY INCREASE

6. Marking of parts / traceability of change	
6.1 Description	Change is visible in the marking with PP code changing - from AA : ASE KaoHsiung (Taiwan) or - from A5 : Amkor ATT (Taiwan) - to GN : JCAP (China) Please refer to PCN 16402_Additional information.pdf document for further details.

7. Timing / schedule	
7.1 Date of qualification results	2027-01-06
7.2 Intended start of delivery	2027-01-15
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	16402 MDRF-GPAM-RER2618 PCN16402 - JCAP (China) additional source for WLCSP package - reliability plan.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	**Issue Date**	2026-10-28

9. Attachments (additional documentations)
16402 Public product.pdf 16402 MDRF-GPAM-RER2618 PCN16402 - JCAP (China) additional source for WLCSP package - reliability plan.pdf 16402 _Additional information.pdf

10. Affected parts		
10. 1 Current		**10.2 New (if applicable)**
10.1.1 Customer Part No	**10.1.2 Supplier Part No**	**10.1.2 Supplier Part No**
	STM32L476JEY6TR	
	STM32L476JGY6TR	
	STM32L476JGY7TR	
	STM32L476MEY6TR	
	STM32L476MGY6MTR	
	STM32L476MGY6TR	
	STM32L486JGY6TR	

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